

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
- 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
- 5. PACKAGE CODE 5203 IS TO ACCOUNT FOR PGE AND THE BUILT–IN HEAT SPREADER.

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TITLE: 620 I/O TEPBGA, HEAT SPREADER, 29 X 29 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARE10568D		REV: B
	CASE NUMBER: 1588–02		26 NOV 2008
	STANDARD: JEDEC MS–034 AAM–1		